

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-8. (Canceled)

9. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing ~~an amount of a~~ thermally curable epoxide layer epoxy compound on the electronic component ~~sufficient to form a layer thereof covering the component, the epoxy compound having included therein~~ the epoxide layer including therein at least one light absorbing material; and

(b) directing laser radiation having a wavelength between about 600 and 1000 nm onto the thermally curable epoxide layer ~~of thermally curable epoxy compound~~ for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat in the layer, whereby the ~~epoxy compound~~ epoxide layer is cured without external heating.

10. (Original) The method of claim 9, wherein said light absorbing material is carbon black.

11. (Original) The method of claim 9, wherein said light absorbing material is a dye.

12. (Original) The method of claim 9, wherein said light absorbing material is a powdered metal.

13. (Previously Presented) The method of claim 9, wherein said laser radiation has a wavelength of about 808 nm.

14. (Previously Presented) The method of claim 9, wherein said laser radiation is produced by a diode-laser array.

15. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) providing a diode-laser array for delivering radiation laser radiation having a wavelength between about 600 and 1000 nm;

~~(b) providing a thermally curable liquid epoxy compound having included therein at least one material that is strongly absorbing for the wavelength of the laser radiation;~~

~~(b)~~ (e) depositing on the electronic component a thermally curable epoxide layer ~~sufficient amount of said liquid epoxy compound to form a layer thereof~~ covering the component, the epoxide layer including therein at least one light absorbing material;

~~(c)~~ (d) transporting said laser radiation from said diode-laser array, via an optical fiber bundle, to an optical projector for projecting said laser radiation; and

~~(d)~~ (e) projecting said laser radiation onto said thermally curable epoxide layer ~~of liquid epoxy compound~~ for a time period sufficient that the light absorbing material absorbs a portion of the laser radiation and generates heat ~~in the layer~~ whereby the ~~liquid epoxy compound~~ epoxide layer is cured without external heating.

16. (Previously Presented) The method of claim 15, wherein said laser radiation has a wavelength of about 808 nm.

17. (Original) The method of claim 15, wherein said at least one light absorbing material is carbon black.

18. (Currently Amended) The method of claim 15, wherein during step ~~(d)~~ (e) said integrated circuit component is held in a fixed relationship to said optical projector and said laser radiation is projected onto said ~~liquid epoxy compound~~ epoxide layer in the form of a spot having a size sufficient to at least cover the electronic component.

19. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing on the electronic component an amount of thermally curable epoxy compound sufficient to form a thermally curable epoxide layer thereof covering the component, the ~~epoxy compound~~ epoxide layer having included therein at least one light absorbing material;

(b) directing laser radiation having a wavelength between about 600 and 1000 nm into an optical projector arranged to project said laser radiation in the form of a line of said laser radiation;

(c) projecting said line of laser radiation onto said thermally curable epoxide layer of ~~epoxy compound~~ including the light absorbing material; and

(d) during step (c), moving the substrate and said integrated circuit with respect to said optical projector such that said ~~epoxy compound~~ thermally curable epoxide layer on the integrated circuit is exposed to said radiation for a time sufficient that said light absorbing material absorbs a portion of the laser radiation and generates heat in the layer whereby the ~~liquid epoxy compound~~ thermally curable epoxide layer is cured without external heating.

20. (Previously Presented) The method of claim 19, wherein said laser radiation is produced by a diode-laser array.

21. (Original) The method of claim 19, wherein said at least one light absorbing material is carbon black.

22. (Currently Amended) A method of encapsulating an electronic component supported on a substrate, comprising the steps of:

(a) depositing on the electronic component a thermally curable liquid epoxide layer including therein at least one light absorbing material; and

(b) irradiating the epoxide layer with laser light generated by a laser diode array and having a wavelength between 600 and 100nm, the epoxide layer being formulated so that at least 15% of the radiation striking the epoxide layer is absorbed by the at least one light absorbing material in a manner to heat and cure the epoxide layer without external heating.